



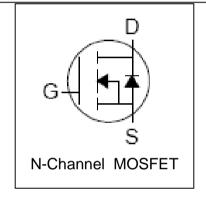
## **Features**

- 60V/70A, RDS (ON) = 6m (Typ.) @Vgs=10V
- Super High Dense Cell Design
- Ultra Low On-Resistance
- 100% avalanche tested
- Lead Free and Green Devices Available (RoHS Compliant)

# **Applications**

DC-DC Converters and Off-line UPS





## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit						
Common Ratings (T <sub>C</sub> =25°C Unless Otherwise Noted)									
$V_{DSS}$	Drain-Source Voltage	60	\/						
$V_{GSS}$	Gate-Source Voltage		±25	V					
$T_J$	Maximum Junction Temperature		175	°C					
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C						
I <sub>S</sub>	Diode Continuous Forward Current	T <sub>C</sub> =25°C	70 <sup>①</sup>	Α					
Mounted on La	Mounted on Large Heat Sink								
I <sub>DP</sub>	300µs Pulse Drain Current Tested	T <sub>C</sub> =25°C	280	Α					
I <sub>D</sub>	Continuous Drain Current(V <sub>GS</sub> =10V)	T <sub>C</sub> =25°C	70 <sup>①</sup>	Α					
ıD		T <sub>C</sub> =100°C	67	A					
$P_D$	Manieron Barras Biasinatias	T <sub>C</sub> =25°C	107	W					
	Maximum Power Dissipation	T <sub>C</sub> =100°C	53.5	W					
$R_{ heta JC}$	Thermal Resistance-Junction to Case	1.4	°C/W						
Drain-Source Avalanche Ratings									
E <sub>AS</sub>	Avalanche Energy, Single Pulsed		225	mJ					



# **Electrical Characteristics** (T<sub>C</sub>=25°C Unless Otherwise Noted)

0	Donomotor	Test Condition		RU6070L			11:0:4	
Symbol	Parameter			Min.	Тур.	Max.	Unit	
Static Cha	racteristics							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA		60			V	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 60V, $V_{GS}$ =0	V			1	^	
			T <sub>J</sub> =85°C			30	μΑ	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{DS}=250$	)μΑ	2	3	4	V	
I <sub>GSS</sub>	Gate Leakage Current	$V_{GS}$ =±25V, $V_{DS}$ =0V				±100	nA	
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =35A			6	7	mΩ	
Diode Cha	aracteristics							
V <sub>SD</sub>	Diode Forward Voltage	I <sub>SD</sub> =35A, V <sub>GS</sub> =0V				1.2	V	
trr	Reverse Recovery Time	-Isp=35A, dlsp/dt=100A/μs			45		ns	
Qrr	Reverse Recovery Charge	isb=33A, disb/di=		90		nC		
Dynamic	© Characteristics							
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F$	=1MHz		1.4		Ω	
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, Frequency=1.0MHz			3450		pF	
C <sub>oss</sub>	Output Capacitance				420			
C <sub>rss</sub>	Reverse Transfer Capacitance				180			
t <sub>d(ON)</sub>	Turn-on Delay Time	VDD=30V, RL=0.9Ω, IDS=35A, VGEN= 10V, RG=4.7Ω			11			
t <sub>r</sub>	Turn-on Rise Time				33		ns	
t <sub>d(OFF)</sub>	Turn-off Delay Time				41			
t <sub>f</sub>	Turn-off Fall Time			25				
Gate Cha	rge Characteristics 5							
Qg	Total Gate Charge	V <sub>DS</sub> =48V, V <sub>GS</sub> = 10V, I <sub>DS</sub> =35A			45		nC	
$Q_{gs}$	Gate-Source Charge				12			
$Q_{gd}$	Gate-Drain Charge				16			
		•						

Notes: ①Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 60A.

②Pulse width limited by safe operating area.

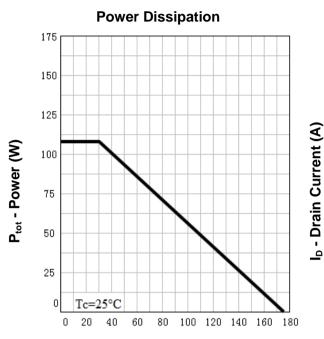
 $<sup>\ \ \, \</sup>mbox{(3)}\mbox{Limited by $T_{Jmax}$, $I_{AS}$ =30A, $V_{DD}$ = 48V, $R_G$ = 50 $\Omega$ , Starting $T_J$ = 25°C.$ 

④Pulse test ; Pulse width≤300μs, duty cycle≤2%.

⑤Guaranteed by design, not subject to production testing.



# **Typical Characteristics**



Drain Current

90

75

60

45

30

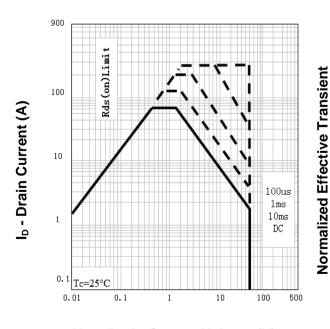
Tc=25°C,Vg=10V

0 20 40 60 80 100 120 140 160 180

T<sub>i</sub> - Junction Temperature (°C)

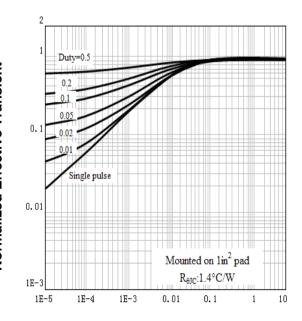
T<sub>i</sub> - Junction Temperature (°C)

### **Safe Operation Area**



V<sub>DS</sub> - Drain-Source Voltage (V)

### **Thermal Transient Impedance**

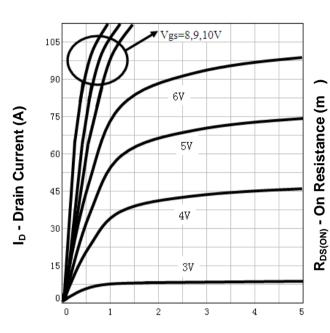


**Square Wave Pulse Duration (sec)** 



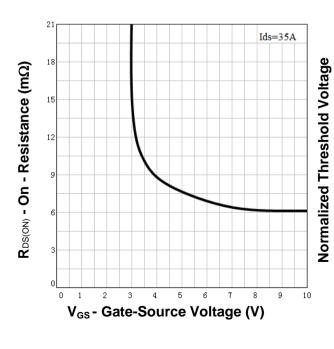
# **Typical Characteristics**

# **Output Characteristics**

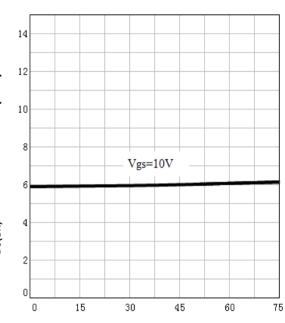


V<sub>DS</sub> - Drain-Source Voltage (V)

### **Drain-Source On Resistance**

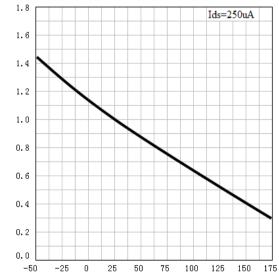


#### **Drain-Source On Resistance**



I<sub>D</sub> - Drain Current (A)

## **Gate Threshold Voltage**

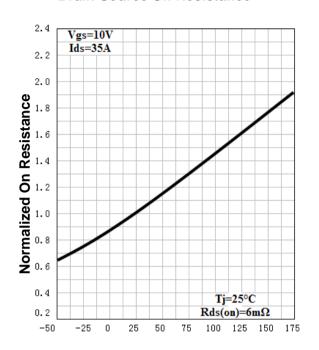


T<sub>i</sub> - Junction Temperature (°C)



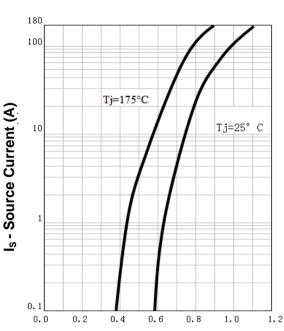
# **Typical Characteristics**

#### **Drain-Source On Resistance**



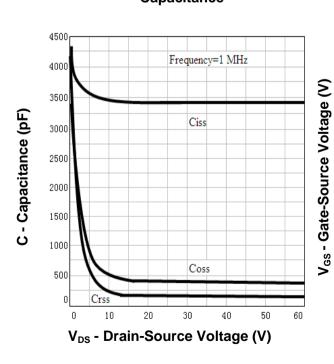
T<sub>j</sub> - Junction Temperature (°C)

#### **Source-Drain Diode Forward**

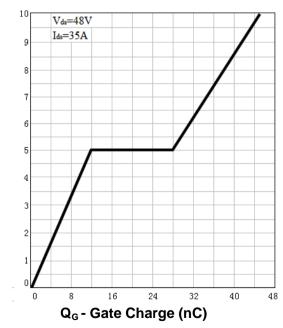


V<sub>SD</sub> - Source-Drain Voltage (V)

# Capacitance

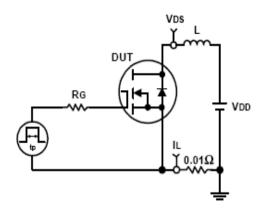


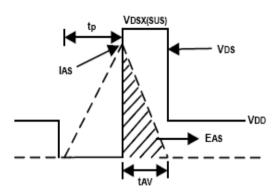
## **Gate Charge**



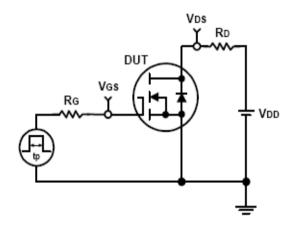


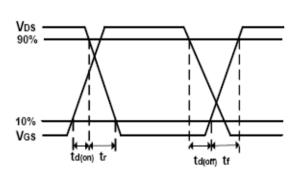
# **Avalanche Test Circuit and Waveforms**





# **Switching Time Test Circuit and Waveforms**







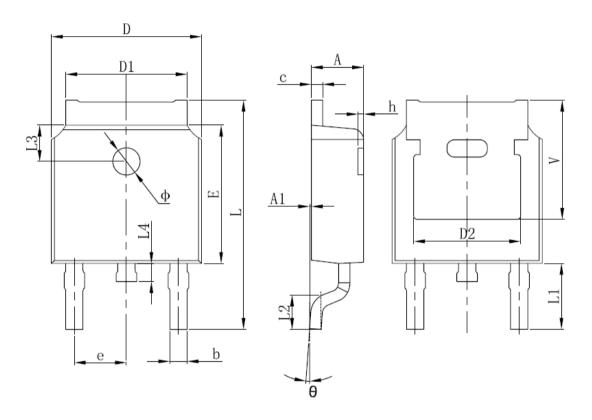
# **Ordering and Marking Information**

Device	Marking	Package	Packaging	Quantity	Reel Size	Tape width
RU6070L	RU6070L	TO-252	Tape&Reel	2500	13''	16mm



# **Package Information**

TO252-2L



SYMBOL -	MM		INCH		ara mor	MM		INCH	
	MIN	MAX	MIN	MAX	SYMBOL	MIN	MAX	MIN	MAX
A	2.200	2.400	0.087	0.094	L	9.800	10.400	0.386	0.409
A1	0.000	0.127	0.000	0.005	L1	2.900 REF.		0.114 REF.	
b	0.660	0.860	0.026	0.034	L2	1.400	1.700	0.055	0.067
С	0.460	0.580	0.018	0.023	L3	1.600 REF.		0.063REF.	
D	6.500	6.700	0.256	0.264	L4	0.600	1.000	0.024	0.039
D1	5.100	5.460	0.201	0.215	Φ	1.100	1.300	0.043	0.051
D2	4.830 REF.		0.190 REF.		θ	0°	8°	0°	8°
Е	6.000	6.200	0.236	0.244	h	0.000	0.300	0.000	0.012
e	2.186	2.386	0.086	0.094	V	5.350 REF.		0.211 REF.	

ALL DIMENSIONS REFER TO JEDEC STANDARD DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS



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